1. Company Status
2. Products and Services
3. Significant Achievements
4. Organization Chart
5. Total Quality
6. Total Satisfaction
7. Major Customers
8. Trend of Equipment Investment
9. Major Production Equipment
10. Available Technologies & Processes
11. Major Strengths
12. R&D Partner - ITRI & CSIST
13. Technical Service Partner - CMC
14. Market Sales by Region
15. Our Focus
16. Major Objectives for 2011
17. Target Market Segments
## 1. Company Status

<table>
<thead>
<tr>
<th>Address</th>
<th>Taipei</th>
<th>Chung-Li</th>
<th>Philippine Plant I</th>
<th>Philippine Plant II</th>
</tr>
</thead>
<tbody>
<tr>
<td>55 Lane 365, Yingtao Rd., Yingko, Taipei Hsien, 239 Taiwan</td>
<td>8F,No. 27, Ji-Lin Rd., Chung-Li Industry Park, Tao-Yuan Hsien, 320 Taiwan</td>
<td>Lot 15 Road 3 Cermelray Ind’l Park Canlubang, Calamba City, Philippines</td>
<td>103 Prosperity Ave., Carmelray Ind’l Park Canlubang, Calamba City Philippines</td>
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<tr>
<td>Established</td>
<td>August 1975</td>
<td>September 1994</td>
<td>April 2008</td>
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<tr>
<td>Employees</td>
<td>804</td>
<td>302</td>
<td>769</td>
<td>928</td>
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<tr>
<td>Tel:</td>
<td>886-2-2679-0122</td>
<td>886-3-433-5998</td>
<td>63-49-549-2952</td>
<td>63-49-549-2940</td>
</tr>
<tr>
<td>Fax:</td>
<td>886-2-2670-0122</td>
<td>886-3-433-5995</td>
<td></td>
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<tr>
<td>Web Site:</td>
<td><a href="http://www.theil.com">www.theil.com</a></td>
<td></td>
<td><a href="http://www.tonghsing.ph">www.tonghsing.ph</a></td>
<td></td>
</tr>
<tr>
<td>Email:</td>
<td><a href="mailto:Chiashychang@mail.theil.com.tw">Chiashychang@mail.theil.com.tw</a></td>
<td></td>
<td></td>
<td><a href="mailto:info@net.tonghsing.ph">info@net.tonghsing.ph</a></td>
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<td><a href="mailto:Sophia_chen@mail.theil.com.tw">Sophia_chen@mail.theil.com.tw</a></td>
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</tbody>
</table>
Contract Manufacturing for Microelectronic Packaging and Ceramic Thick Film/Thin Film Substrate Fabrication.

- RF Modules for Cellular Handsets, WLAN, and WiMax
- SiP Packaging for WLAN, UWB, and PAN
- MEMS Packaging
- CMOS Image Sensor Packaging
- Reconstruction Wafer
- Chip Probing and Final Test
- PCB assembly with SMT and/or COB Processes
- Automotive Hybrids
- Thin Film on Alumina and AlN
- Thick Film on Alumina
3. Significant Achievements

1974  Tong Hsing Established
1976  Started Production of Alumina Ceramic Substrates
1977  Started Production of Thick Film Print and Fire
1979  Started Production of Hybrid Modules
1986  Shipped 500K Modules of Electronic Fuse
1989  Received IECQ Manufacturer Approval
1993  Started Large Scale Production of Thick Film Copper Process
1993  Received ISO-9002 Certification
1994  Established Tong Hsing Electronics (Philippines) Inc.
1995  Started Production of Photo-Sensitive Thick Film Circuits
1996  Established CIM System to Track the WIP through LAN
1997  Started Mass Production of CDMA Power Amplifier Modules
1998  Received QS-9000/ISO-9001 Certification
1999  Started Mass Production of GSM Power Amplifier Modules
2001  Started Production of Thin Film DPC Substrate Fabrication
2002  Received ISO14000 Certification
2006  Received TS16949 and OHSAS 18001 Certification
2007  IPO at Taiwan Stock Exchange on Nov.15th
2008  Won the “Excellent Enterprise Innovation Award” from MOEA (Ministry of Economic Affairs)
2009  Received AS9100 Certification.
2010  Acquired Impac to form a new Image Sensor Group
      Achieved “0” ppm for All Products Shipped to Automotive Customers for two consecutive years.
4. Organization Chart
- Tong Hsing Electronic Ind., Ltd.

- Chairman & CEO
  Jay Yang

- President
  Henry Liu

- Auditing
  Mark Lee

- Vice President Finance
  Kevin Lai

- Vice President Marketing & Innovation
  Heinz Ru

- Vice President Operations of THEIL
  Mike Chiu

- Vice President Operations of THECL
  SY Huang

- Vice President Operations of THEPI
  Jenson Lin
4.1 Organization Chart - Taiwan Operations

Vice President
Michael Chiu

R&D
- Substrate Pkg
- RF Pkg
- ADE
- IMS

Manufacturing
- Substrate Manufacturing
- Hybrid Pkg
- Assembling & Testing

QA
- IQC
- QC
- QA

Material Control
- Warehouse

Purchasing
- Outsourcing

Administration
- HRD
- General Affairs

OHS
- Facilities

IT
- Hardware
- Software

Company Confidential
4.3 Organization Chart - ChungLi Operations

Vice President
SY Huang

- Manufacture
  - Chip Probing
  - Restructure Wafer
  - Facility

- Engineering
  - Chip Probing
  - Restructure Wafer

- Quality Reliability Assurance
  - Quality Control
  - Quality Assurance

- Logistics
  - Bond & I/Export
  - Administration
  - Warehouse

Company Confidential
4.4 Organization Chart
- Philippine Operations

Vice President
Jenson Lin

MIS

VP's Office
Executive Secretary

Finance
- Finance & Treasury
- General Accounting
- Cost Accounting
- Management Advisory Services

Administration
- Purchasing
- Traffic
- Facilities

HR
- HR Employment & Learning
- HR Relations & Welfare
- Facilities

Operations
- DPC Mfg.
- A&TE
- IP
- Module Assy
- Module Assy

Quality Mngt.
- Quality Control
- Document Control Center
- Quality Eng'g
- Calibration

PPIC
- Prod. Plan
- MCIC
- Product Dev Technologies

Advanced Eng‘g

Company Confidential
Total: 2803
(THETP: 804, THECL: 302, THEPI: 1697)
Commitment:

Excellence in Quality is at the Forefront of all our activities. At Tong Hsing there is no Compromise of Quality.

Jay Yang
Chairman and CEO
Commitment:

To be your Preferred Manufacturing Partner. We will provide our Best Quality, Delivery and Service to Accomplish your 100% Satisfaction.

Jay Yang
Chairman and CEO
7. Major Customers

- AEI
- Advanced Bionics
- Anadigics
- Aptina Imaging
- DDC
- Delphi
- National Semiconductor
- OmniVision Technologies
- Sensata
- SiGe
- Skyworks
- TI

We look forward to our continuing expansion and development to better serve our customers.
8. Trend of Equipment Investment
Comparison 1999 through 2010

[Bar chart showing the trend of equipment investment from 1999 to 2010. The vertical axis represents the millions of US dollars, and the horizontal axis represents the years from 1999 to 2010. The chart illustrates a significant increase in investment from 2000 to 2010.]
## 9. Major Production Equipment

<table>
<thead>
<tr>
<th>Equipment</th>
<th>Quantity</th>
<th>Equipment</th>
<th>Quantity</th>
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<tbody>
<tr>
<td>Laser Machining</td>
<td>12</td>
<td>Chipmounter</td>
<td>21</td>
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<tr>
<td>Printer</td>
<td>44</td>
<td>Cleaner</td>
<td>29</td>
</tr>
<tr>
<td>Furnace</td>
<td>13</td>
<td>Wafer Mounter</td>
<td>4</td>
</tr>
<tr>
<td>YAG Laser Trimmer</td>
<td>4</td>
<td>Reflow</td>
<td>8</td>
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<tr>
<td>Sputter System</td>
<td>4</td>
<td>Die Bonder</td>
<td>57</td>
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<tr>
<td>Mask Aligner/Exposure</td>
<td>14</td>
<td>Wire Bonder</td>
<td>116</td>
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<tr>
<td>Developer</td>
<td>4</td>
<td>Flip Chip Bonder (GGI/C4)</td>
<td>4</td>
</tr>
<tr>
<td>Plating Lines--Cu</td>
<td>12</td>
<td>Plasma Cleaner</td>
<td>10</td>
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<tr>
<td>Plating Lines--Ni/Au</td>
<td>5</td>
<td>Transfer Molder</td>
<td>9</td>
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<tr>
<td>Plating Ni/Pd/Au</td>
<td>1</td>
<td>Dispenser</td>
<td>33</td>
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<tr>
<td>E'less-Cu</td>
<td>2</td>
<td>Dicing Saw</td>
<td>61</td>
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<tr>
<td>E'less- Ag</td>
<td>2</td>
<td>Taping</td>
<td>3</td>
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<tr>
<td>E'less--Cu/Ni/Au</td>
<td>1</td>
<td>Detaping</td>
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<tr>
<td>Strip &amp; Etch</td>
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<td>Oven</td>
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<tr>
<td>Surface Measurement</td>
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<td>Sorter</td>
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<tr>
<td>AOI</td>
<td>7</td>
<td>AVI</td>
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<tr>
<td>Flying Probe System</td>
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<td>FT Handler</td>
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<tr>
<td>Grinding/Lapping</td>
<td>10</td>
<td>Prober</td>
<td>18</td>
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<tr>
<td>Laser Marking Machine</td>
<td>20</td>
<td>Tester</td>
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</table>

*Updated Nov. 2010*
<table>
<thead>
<tr>
<th>Assembly Technologies</th>
<th>Packaging Technologies</th>
<th>Substrate Technologies</th>
<th>Laser Mfg. Technologies</th>
</tr>
</thead>
<tbody>
<tr>
<td>* SMT</td>
<td>* Metal Lid</td>
<td>* Thick Film</td>
<td>* Precision Substrate Scribing &amp; Drilling</td>
</tr>
<tr>
<td>* Chip &amp; Wire</td>
<td>* Liquid Encapsulation</td>
<td>* Thin Film</td>
<td>* Resistor Trimming(&lt;=0.1%), Active Functional Trimming</td>
</tr>
<tr>
<td>* Heavy Aluminum Wire</td>
<td>* Overmold</td>
<td>* Double Side Circuitry with Through Holes</td>
<td>*2D Barcode on Ceramic</td>
</tr>
<tr>
<td>* Automatic Solder Die Attach</td>
<td>* Glass Lid</td>
<td></td>
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</tbody>
</table>

| Reconstuction Wafer                        | Testing                                       |                                          |                                               |
| * Wafer Grinding                          | * Final Test                                  |                                          |                                               |
| * AVI                                     | * Chip Probing                                |                                          |                                               |
|                                          | * Sawing                                      |                                          |                                               |
|                                          | * Sorting                                     |                                          |                                               |
11. Major Strengths

- Flexibility
- Technical Innovation
- Continuous Improvement & Growth
- Excellent High Volume Production Capacity
- Superior Supporting Infrastructure in Northern Taiwan
- Abundant Supply of Human Resources for Semiconductor Packaging in the Philippines
- Superb Customer Satisfaction
- Strong R & D Partners
12. R&D Partners (ITRI & CSIST)

The Industrial Technology Research Institute (ITRI)
The Chung Shan Institute of Science and Technology (CSIST)

- **ITRI**: a Taiwan research institute which serves to support local industries in R&D especially in the information and communication technologies.
  - Field of Services: Communication and Optoelectronics, Precision Machinery and MEMS, Materials and Chemical Engineering, Biomedical Technology, Sustainable Development, and Nanotechnology.

- **CSIST**: a research institute for national Defense, serves to integrate all the local industries in Taiwan, especially Information & communication industries.
CMC Laboratories, Inc.

• Core expertise: material science on interconnect applications including all aspects of packaging and assembly.

• Services:
  - Failure analysis
  - Destructive physical analysis
  - Electrical characterization
  - Thermal characterization
  - Process development support to engineering
  - Yield enhancement support to manufacturing
  - Customized reliability testing
  - Technical market analysis on electronic packaging industry
14. Market Sales by Region

Europe: 28%
Asia: 8%
N. America: 62%
Taiwan: 2%
15. Our Focus

- Customer Satisfaction
- Quality
- Turnaround/Delivery Time
- Productivity
16. Major Objectives for 2011

- Become the leading foundry service provider of RF Modules, SiP and MEMS packaging in Asia Pacific
- Continue the expansion of the production scale of Thin Film DPC substrates used in High Brightness LED’S, solar cell, and Electrical Vehicle
- Ramp up the production of ultra high brightness LED used in projectors
- Expand the business in commercial aircraft industry
- Expand the business in Fuel Cell
- Ramp up the production of medical electronic circuits
- Continue the expansion of the production scale of Image Sensor, including Chip Probing, Reconstruction Wafer, Assembling and Final Test
17. Target Market Segments

- RF Modules, PA and Front-end Modules for Handsets and WLANs
- Special Packaging for MEMS devices
- SiP for PAN, WLAN and GPS
- Image Sensor
- Modules for the Automotive Electronic Industry
- Ultra High Power LED Packaging
- Medical Electronics
- Electronics for Commercial Aircraft
- Thin Film (DPC) Metalized Ceramic Substrates for High Brightness LED, Solar Cell and Hybrid Electrical Vehicle
- Fuel Cell